Ordering Information

Part Number	Slew Rate	Output Discharge	Package	Environmental
AOZ1320CI-01*	1ms	No	SOT23-6	RoHS Compliant
AOZ1320CI-02	0.5µs	No	SOT23-6	RoHS Compliant
AOZ1320CI-03*	100µs	Yes	SOT23-6	RoHS Compliant
AOZ1320CI-04	1ms	Yes	SOT23-6	RoHS Compliant
AOZ1320CI-05	0.5µs	Yes	SOT23-6	RoHS Compliant
AOZ1320CI-06*	100µs	No	SOT23-6	RoHS Compliant
AOZ1320CI-07	4.5ms	Yes	SOT23-6	RoHS Compliant
AOZ1320DI-01	1ms	No	2x2 DFN-8	RoHS Compliant
AOZ1320DI-02	0.5µs	No	2x2 DFN-8	RoHS Compliant
AOZ1320DI-03	100µs	Yes	2x2 DFN-8	RoHS Compliant
AOZ1320DI-04	1ms	Yes	2x2 DFN-8	RoHS Compliant
AOZ1320DI-05	0.5µs	Yes	2x2 DFN-8	RoHS Compliant
AOZ1320DI-06	100µs	No	2x2 DFN-8	RoHS Compliant

* Contact manufacturer for availability.

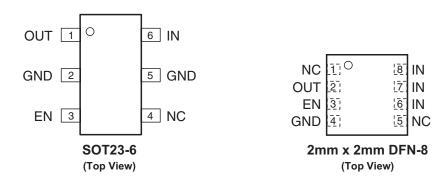
All AOS products are offered in packages with Pb-free plating and compliant to RoHS standards.

Green Products use reduced levels of Halogens, and are also RoHS compliant.

Please visit www.aosmd.com/media/AOSGreenPolicy.pdf for additional information.

Pin Configuration

een



Pin Description

	Pin N	umber	
Pin Name	DFN-8 SOT23-6		Pin Function
IN	6, 7, 8 6		Input. IN is the drain of the P-channel MOSFET. It is the supply input of the IC.
GND	4 2, 5		Ground.
OUT	2	1	Output. OUT is the source of the P-channel MOSFET.
EN	3 3		Enable. The P-channel MOSFET turns on when EN is logic HIGH.
NC	1, 5	4	No Connect. This pin is not internally connected.



Absolute Maximum Ratings Exceeding the Absolute Maximum ratings may damage the device.

Parameter	Rating
IN to GND	-0.3V to 6V
EN to GND	-0.3V to 6V
OUT to GND	-0.3V to V _{IN} +0.3V
Maximum Continuous Switch Current	
SOT23-6	1.6A
2x2 DFN-8	2.3A
Maximum Pulsed Current (V _{IN} > 2.5V)	6A
Maximum Pulsed Current (V _{IN} < 2.5V)	3A
Storage Temperature (T _S)	-65°C to +150°C
ESD Rating ⁽¹⁾	4.5kV

Note:

1. Devices are inherently ESD sensitive, handling precautions are required. Human body model is a 100pF capacitor discharging through a 1.5k³/₄ resistor.

Recommend Operating Ratings

The device is not guaranteed to operate beyond the Maximum Operating Ratings.

Parameter	Rating
Operating Junction Temperature (T _J)	-40°C to +150°C
Power Dissipation	
SOT23-6	0.65W
2x2 DFN-8	1.54W
Package Thermal Resistance	
SOT23-6 (Θ _{JA})	191°C/W
2x2 DFN-8 (_{9JA})	81°C/W



Electrical Characteristics

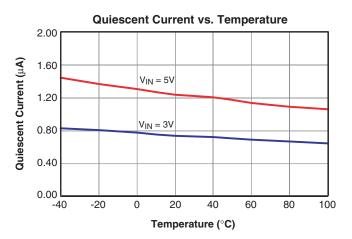
 $T_A = 25^{\circ}$ C, $V_{IN} = V_{EN} = 5$ V, unless otherwise specified[.] Specifications in **BOLD** indicate an ambient temperature range of -40°C to +85°C.

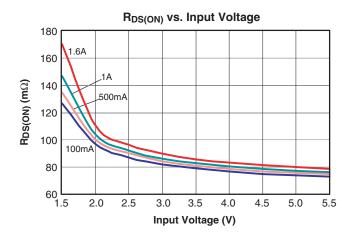
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
V _{IN}	Operating Voltage Range		1.8	5	5.5	V
V _{UVLO}	Under-Voltage Lockout Threshold	V _{IN} Falling V _{IN} Rising	0.7 1.0	0.9 1.2	1.3 1.6	V
I _{IN}	Input Quiescent Current	EN = 5.0V EN = GND		1.2	4 1	μA
I _{OUT(OFF)}	Switch Leakage Current	V _{EN} < V _{IL(max)} , V _{OUT} = 0V			1	μA
R _{DS(ON)}	Switch On-Resistance	$V_{IN} = 5.0V$ $V_{IN} = 4.2V$ $V_{IN} = 3.0V$ $V_{IN} = 1.8V$		75 78 81 109	100 105 110 150	mΩ
V _{IL}	Enable Input-Low Voltage				0.8	V
V _{IH}	Enable Input-High Voltage	$V_{IN} = 1.8V \text{ to } 2.0V$ $V_{IN} = 2.0V \text{ to } 4.2V$ $V_{IN} = 4.2V \text{ to } 5.5V$	1.8 2.0 2.4			V
I _{EN}	Enable Input Leakage Current	V _{EN} = 5.5V			1	μA
AOZ1320-01	, -04					
T _{D(ON)}	Output Turn-on delay	$R_L = 10\Omega$, See Figure 1		200	300	μs
Τ _R	Output Rise-time	$R_L = 10\Omega$, See Figure 1		1000	1500	μs
T _{D(OFF)}	Output Turn-off delay	$R_L = 10\Omega$, See Figure 1		20	30	μs
AOZ1320-02	2, -05					
T _{D(ON)}	Output Turn-On Delay	$R_L = 10\Omega$, See Figure 1		2	4	μs
Τ _R	Output Rise-Time	$R_L = 10\Omega$, See Figure 1		0.5	1	μs
T _{D(OFF)}	Output Turn-Off Delay	$R_L = 10\Omega$, See Figure 1		20	30	μs
AOZ1320-03	3, -06		•		•	
T _{D(ON)}	Output Turn-On Delay	$R_L = 10\Omega$, See Figure 1		20	130	μs
Τ _R	Output Rise Time	$R_L = 10\Omega$, See Figure 1		100	150	μs
T _{D(OFF)}	Output Turn-Off Delay	$R_L = 10\Omega$, See Figure 1		20	30	μs
AOZ1320-07	7		•		•	
T _{D(ON)}	Output Turn-On Delay	$R_L = 10\Omega$, See Figure 1		450	850	μs
T _R	Output Rise Time	$R_L = 10\Omega$, See Figure 1		4500	7500	μs
T _{D(OFF)}	Output Turn-Off Delay	$R_L = 10\Omega$, See Figure 1		20	30	μs
AOZ1320-03	3, -04, -05, -07	•		•	•	•
R _{DIS}	Output Pull-Down Resistance in Shutdown	V _{EN} < V _{IL(max)}		180	250	Ω

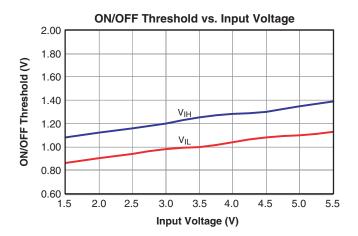


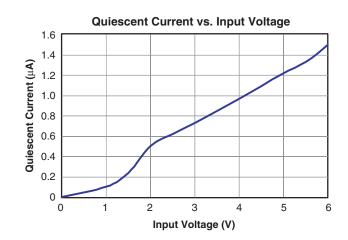
AOZ1320

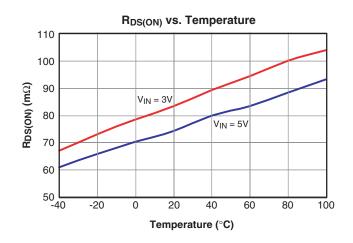
Typical Performance Characteristics

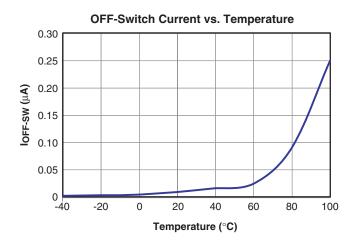








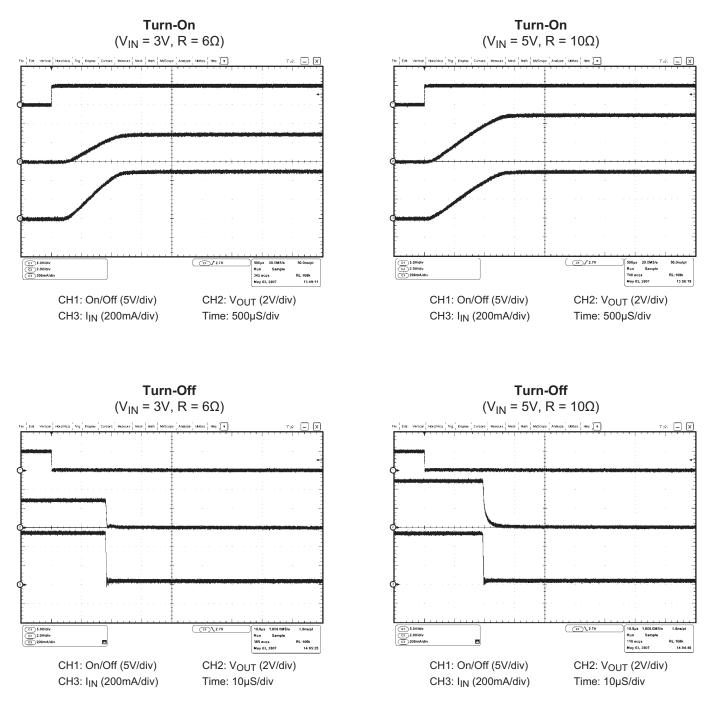






Typical Characteristics

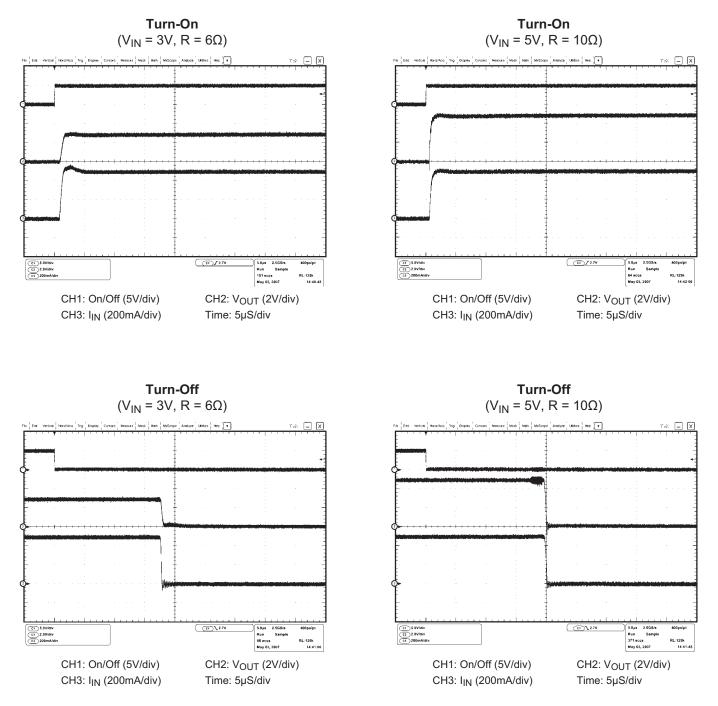
AOZ1320-01, AOZ1320-04





Typical Characteristics (Continued)

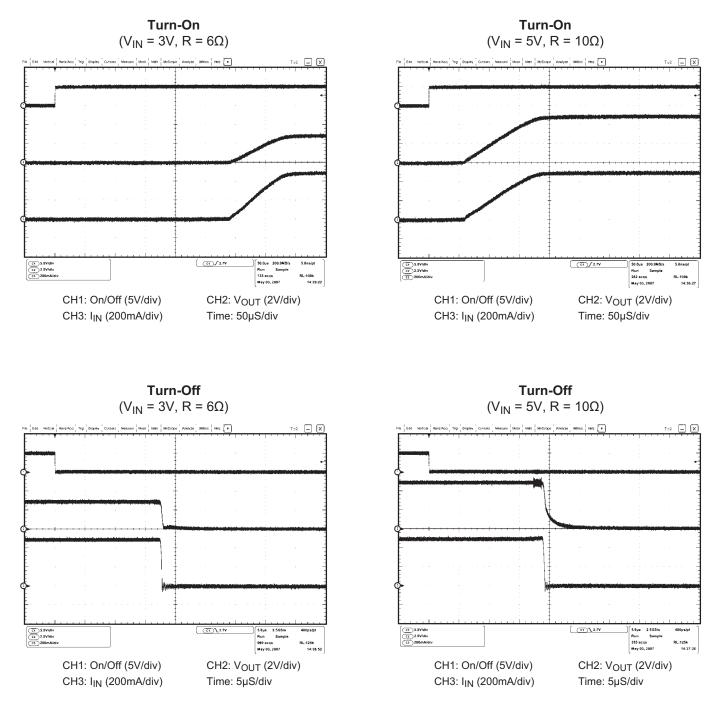
AOZ1320-02, AOZ1320-05





Typical Characteristics (Continued)

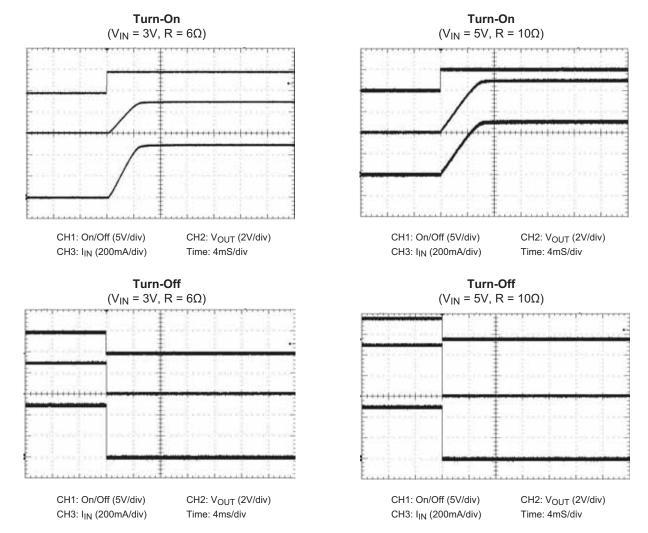
AOZ1320-03, AOZ1320-06



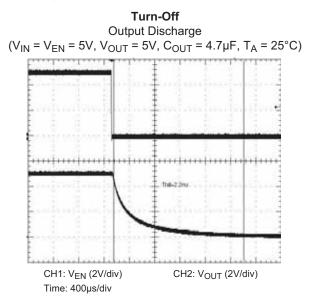


Typical Characteristics (Continued)

AOZ1320-07



AOZ1320-03, AOZ1320-04, AOZ1320-05, AOZ1320-07



Rev. 1.8 August 2013

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Timing Diagram

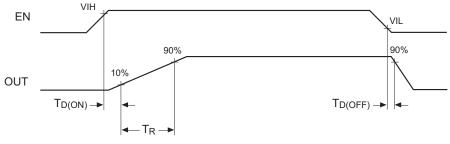


Figure 1. AOZ1320 Timing Diagram

Functional Block Diagram

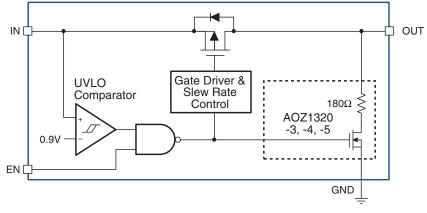


Figure 2. Functional Block Diagram



Detailed Description

Slew Rate Control

The AOZ1320 is a family of P-channel high-side load switches with controlled slew rate. The device is enabled when the input voltage is above the Under-Voltage Lockout (UVLO) threshold and the EN pin is high. Once enabled, the gate driver and slew-rate control circuitry immediately raises the source-to-gate voltage of the P-channel MOSFET to its threshold level, and then gradually turns on the MOSFET by linearly increases the source-to-gate voltage. This slow turn-on action effectively limits the input inrush current and provides a nice ramp for the output voltage. After the MOSFET is fully enhanced, the AOZ1320 quickly increases the source-to-gate voltage to the full input voltage to minimize on resistance and reduce power dissipation.

Three slew-rate options are available. AOZ1320-01 and -04 have a slew rate of 1ms, and the AOZ1320-07 has a slew rate of 4.5ms. This option significantly reduces the inrush current when the MOSFET turns on, allowing the use of very small input capacitor. AOZ1320-02 and -05 have no slew rate control and the MOSFET can be turned on within 500ns. This option is suitable for applications that require very fast switching. AOZ1320-03 and -06 have a moderate slew rate to 100µs. The AOZ1320-03, -04, -05, and -07 options include an internal output discharge circuit that quickly discharges the output to ground when the device is disabled.

Input Under-Voltage Lockout

The operating voltage range of AOZ1320 is from 1.8V to 5.5V. An internal UVLO comparator monitors the input voltage. The device is disabled if the input voltage falls below the UVLO threshold (0.9V typical). The UVLO comparator has about 300mV hysteresis.

On/Off Control

The AOZ1320 is enabled when the input voltage is above the UVLO threshold and the EN pin is asserted high. The device is disabled when the input voltage is below the UVLO threshold or the EN pin is asserted low. The EN input is compatible with both TTL and CMOS logic.

Internal Discharge Resistor

The AOZ1320 has an internal 180³/₄ resistor to discharge any remaining voltage from the system to the ground that is store in a capacitive load. This provides a safe shutdown of the system to prevent any damages to the devices. This function is controlled from the Enable pin.

Applications Information

Input Capacitor Selection

Use a 1μ F or larger capacitor for input bypassing. Place the capacitor close to the IN pins of AOZ1320.

Output Capacitor Selection

Use a 0.1μ F or larger capacitor between OUT and GND. The capacitance does not affect the turn-on slew rate. However, a larger capacitor makes the initial turn-on transient smoother.

Thermal Considerations

To ensure proper operation, the maximum junction temperature $(T_{J(MAX)})$ of AOZ1320 should not exceed 150°C. Several factors attribute to the junction temperature rise: load current, MOSFET on resistance $(R_{DS(ON)})$, on-resistance temperature coefficient (T_C) , junction-to-ambient thermal resistance (Θ_{JA}) , and ambient temperature (T_A) . Use the following equation to determine the maximum continuous load current $I_{LOAD(MAX)}$:

$$\sqrt{\frac{T_{J(MAX)} - T_A}{\Theta_{JA} \bullet R_{DS(ON)} \bullet [1 + T_C \bullet (T_{J(MAX)} - T_A)]}}$$

where $R_{DS(ON)}$ is the maximum value of the MOSFET on resistance at 25°C. Please note the maximum load current should not exceed the absolute maximum current rating of the switch. For the SOT-23 package, the absolute maximum current rating is 1.6A. For the 2x2 DFN package, the absolute maximum current rating is 2.3A.

For example, when V_{IN} = 5V, the maximum continuous load current of SOT-23 package at room temperature is:

 $I_{LOAD(MAX)} =$

1	150° C – 25° C	= 2.78 A
N	120° C / W • $100 m\Omega$ • $[1 + 0.0028 • (150^{\circ}$ C - 25° C)]	_

Since the calculated current is greater than the absolute maximum current rating, the maximum load current at V_{IN} = 5V and room temperature is 1.6A.

Exceeding the maximum continuous load current may cause damage to the device. Figure 3 and Figure 4 show the maximum load current as a function of the ambient temperature for SOT23 and 2x2 DFN packages respectively. To ensure proper operation, the load current should not exceed the limits in these two figures.

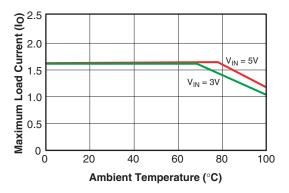


Figure 3. Maximum Load Current Thermal Derating for SOT23 Package

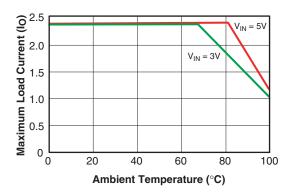


Figure 4. Maximum Load Current Thermal Derating for 2x2 DFN Package

Layout Guidelines

Good PCB is important for improving the thermal performance of AOZ1320. Place the input and output bypass capacitors close to the IN and OUT pins. The input and output PCB traces should be as wide as possible for the given PCB space. Use a ground plane to enhance the power dissipation capability of the device. The AOZ1320 evaluation board can be used as a layout example. The PCB layout of AOZ1320 evaluation board is shown in Figure 5 and 6.

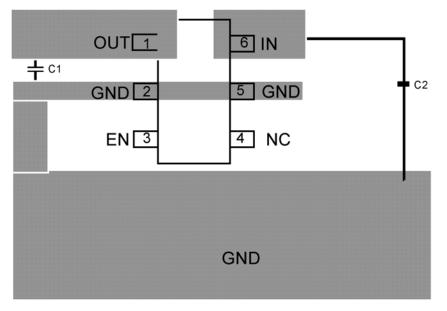


Figure 5. AOZ1320 (SOT23-6) PCB Layout



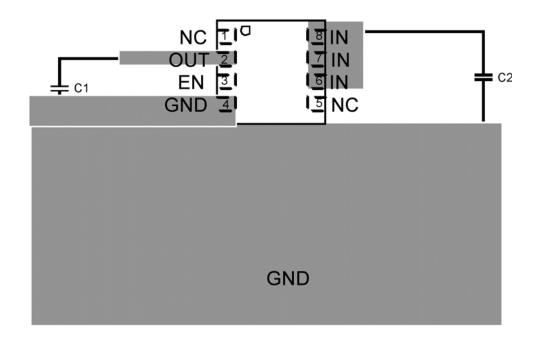
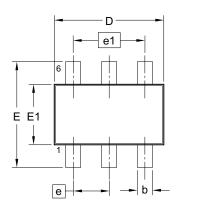
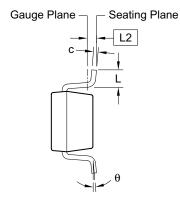


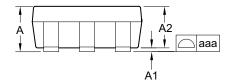
Figure 6. AOZ1320 (DFN2x2) PCB Layout



Package Dimensions, SOT23-6 LP







Dimensions in millimeters

RECOMMENDED LAND PATTERN 2.40 0.63 0.95 UNIT: mm

Dimensi	ions in	miiiim	eters				
Symbols	Min.	Nom.	Max.				
А		_	1.00				
A1	0.00	—	0.10				
A2	0.70	0.88	0.95				
b	0.35	0.40	0.50				
С	0.10	0.13	0.20				
D	2.80	2.90	3.00				
E	2.60	2.80	3.00				
E1	1.50	1.60	1.70				
е	(0.95 BSC	;				
e1		1.90 BSC	;				
L	0.30	0.40	0.60				
L2	0.25 BSC						
aaa		0.10					
θ	0 °	_	8°				

Dimensions in inches

Symbols	Min.	Nom.	Max.			
A	_	_	0.039			
A1	0.00	—	0.004			
A2	0.028	0.035	0.037			
b	0.014	0.016	0.020			
С	0.004	0.005	0.008			
D	0.110	0.114	0.118			
E	0.102	0.110	0.118			
E1	0.059	0.063	0.067			
е	0	.037 BSC				
e1	0	.075 BS	С			
L	0.012	0.016	0.024			
L2	0.010 BSC					
aaa		0.004				
θ	0°	—	8°			

Notes:

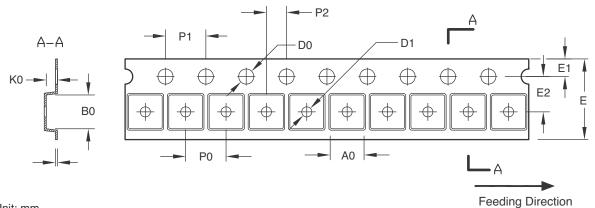
0.80

1. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils each.

- 2. Dimension "L" is measured in gauge plane.
- 3. Tolerance ± 0.100 mm (4 mil) unless otherwise specified.
- 4. Refer to JEDEC MO-193C AB.
- 6. Controlling dimension is millimeter. Converted inch dimensions are not necessarily exact.

Tape and Reel Dimensions, SOT23-6

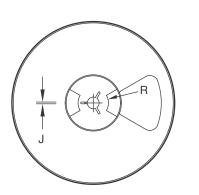
Таре

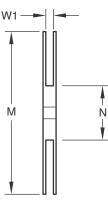


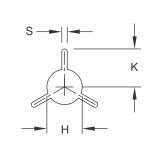
Unit: mm

Package	A0	B0	К0	D0	D1	Е	E1	E2	P0	P1	P2	т
SOT23-5/6L	3.15	3.20	1.40	1.50	1.00	8.00	1.75	3.50	4.00	4.00	2.00	0.23
LP	±0.10	±0.10	±0.10	±0.05	+0.10 / -0	±0.30	±0.10	±0.05	±0.10	±0.10	±0.05	±0.03

Reel



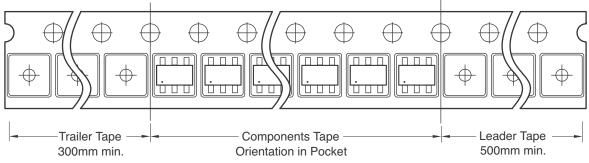




Unit: mm

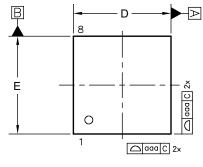
Tape Size	Reel Size	М	N	W1	н	S	К	R	J
8mm	ø177.8	ø177.8 Max.	55.0 Min.	8.4 +1.50 / -0.0	13.0 +0.5 / -0.2	1.5 Min	10.1 Min.	12.7	4.0 ±0.1

Leader/Trailer and Orientation

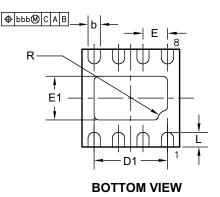


ALPHA & OMEGA SEMICONDUCTOR

Package Dimensions, DFN 2x2 8L

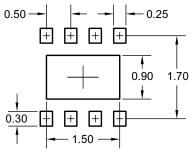








RECOMMENDED LAND PATTERN



UNIT: mm

Dimensions in millimeters

Dimensions in inches

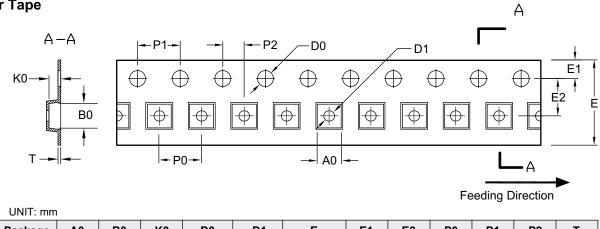
					Dimer	1310113		100
Symbols	Min.	Nom.	Max.		Symbols	Min.	Nom.	Max.
А	0.70	0.75	0.80		А	0.028	0.030	0.031
A1	0.00	0.02	0.05		A1	0.000	0.001	0.002
b	0.18	0.25	0.30		b	0.007	0.010	0.012
С	0.15	0.20	0.25	1	С	0.006	0.008	0.010
D	2	2.00 BSC	;		D	0	.079 BS	С
D1	1.35	1.50	1.60		D1	0.053	0.059	0.063
Е	2.00 BSC				Е	0.079 BSC		
E1	0.75	0.90	1.00		E1	0.030	0.035	0.039
е	().50 BSC)		е	0	.020 BS	C
L	0.20	0.30	0.40		L	0.008	0.012	0.016
R		0.20			R		0.008	
aaa	0.15				aaa		0.006	
bbb	0.10				bbb	0.004		
CCC	0.10			CCC		0.004		
ddd		0.08			ddd		0.003	
				-				

Notes:

- 1. Dimensions and tolerances conform to ASME Y14.5M-1994.
- 2. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.
- 3. Dimension b applied to metallized terminal and is measured between 0.10mm and 0.30mm from the terminal tip. If the terminal has the optional radius on the other end of the terminal, dimension b should not be measured in that radius area.
- 4. Coplanarity ddd applies to the terminals and all other bottom surface metallization.

Tape and Reel Dimensions, DFN 2 x 2

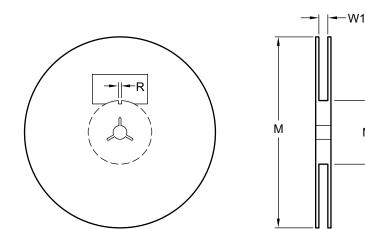
Carrier Tape

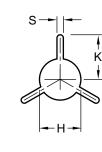


Package	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	Т
DFN 2x2	2.25	2.25	1.00	1.50	1.00	8.00	1.75	3.50	4.00	4.00	2.00	0.254
	±0.05	±0.05	±0.05	+0.10/-0	+0.25/-0	+0.30/-0.10	±0.10	±0.05	±0.10	±0.10	±0.10	±0.02

Ν

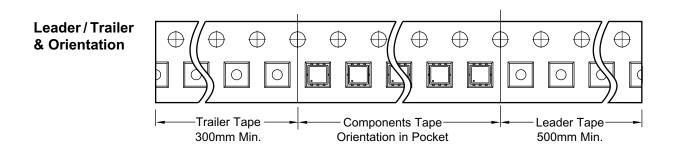
Reel





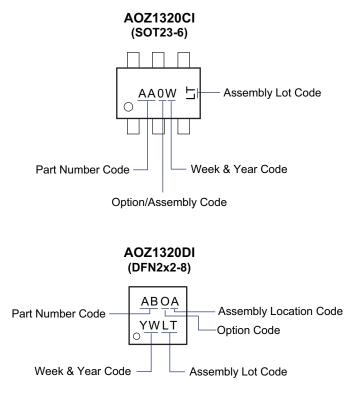
UNIT: mm

Tape Size	Reel Size	М	Ν	W1	Н	S	К	R
8mm	ø180	ø180.00	60.0	8.4	13.0	1.5	13.5	3.0
		±0.50	±0.50	+1.5/-0.0	±0.20	Min.	Min.	±0.50





Package Marking



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